



IPC J-STD-001H

# Requirements for Soldered Electrical and Electronic Assemblies

If a conflict occurs between the English and translated versions of this document, the English version will take precedence.

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Users of this publication are encouraged to participate in the development of future revisions.

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# Table of Contents

<b>1.0 GENERAL</b> .....	1	1.12 Inspection Methodology .....	6
1.1 Scope .....	1	1.12.1 Process Verification Inspection.....	6
1.2 Purpose.....	1	1.12.2 Visual Inspection.....	6
1.3 Classification .....	1	1.13 Facilities .....	7
1.4 Measurement Units and Applications .....	1	1.13.1 Environmental Controls .....	7
1.4.1 Verification of Dimensions .....	2	1.13.2 Field Assembly Operations.....	8
1.5 Definition of Requirements .....	2	1.13.3 Health and Safety .....	8
1.5.1 Hardware Defects and Process Indicators .....	2	1.14 Electrostatic Discharge (ESD).....	8
1.5.2 Material and Process Nonconformance .....	2	<b>2.0 APPLICABLE DOCUMENTS</b> .....	9
1.5.3 Procedures for Specialized Technologies.....	2	2.1 IPC .....	9
1.6 Process Control Requirements .....	3	2.2 JEDEC .....	9
1.6.1 Opportunities Determination .....	3	2.3 Joint Industry Standards .....	10
1.6.2 Statistical Process Control.....	3	2.4 ASTM .....	10
1.7 Order of Precedence .....	4	2.5 EOS/ESD Association, Inc. ....	10
1.7.1 Appendices.....	4	2.6 International Electrotechnical Commission .....	10
1.8 Terms and Definitions.....	4	2.7 SAE International .....	10
1.8.1 Circumferential Solder Separation (Area Void of Solder) .....	4	2.8 Military Standards .....	10
1.8.2 Diameter .....	4	2.9 Aerospace Industries Association / National Aeronautics Standards .....	10
1.8.3 Disposition .....	4	<b>3.0 MATERIALS, COMPONENTS AND EQUIPMENT REQUIREMENTS</b> .....	11
1.8.4 Electrical Clearance .....	4	3.1 Materials.....	11
1.8.5 Engineering Documentation .....	4	3.2 Solder .....	11
1.8.6 FOD (Foreign Object Debris) .....	4	3.2.1 Solder – Pb-Free .....	11
1.8.7 High Voltage .....	4	3.2.2 Solder Purity Maintenance .....	11
1.8.8 Manufacturer .....	5	3.3 Flux .....	12
1.8.9 Objective Evidence .....	5	3.3.1 Flux Application .....	12
1.8.10 Process Control.....	5	3.4 Adhesives .....	12
1.8.11 Proficiency.....	5	3.5 Chemical Strippers.....	12
1.8.12 Solder Destination Side .....	5	3.6 Components.....	13
1.8.13 Solder Source Side .....	5	3.6.1 Component and Seal Damage .....	13
1.8.14 Solder Void.....	5	3.6.2 Coating Meniscus .....	13
1.8.15 Supplier .....	5	3.7 Tools and Equipment.....	13
1.8.16 Tempered Leads .....	5	<b>4.0 GENERAL SOLDERING AND ASSEMBLY REQUIREMENTS</b> .....	15
1.8.17 User .....	5	4.1 Solderability .....	15
1.8.18 Wire Overlap.....	5	4.2 Solderability Maintenance .....	15
1.8.19 Wire Overwrap.....	5	4.3 Removal of Component Surface Finishes .....	15
1.9 Requirements Flowdown .....	6	4.3.1 Gold Removal.....	15
1.10 Personnel Proficiency .....	6	4.3.2 Other Metallic Surface Finishes Removal .....	15
1.10.1 X-Ray Specific Personnel Proficiency .....	6		
1.11 Acceptance Requirements.....	6		

4.4	Thermal Protection .....	15	5.4.1	General Requirements .....	23
4.5	Rework of Nonsolderable Parts .....	16	5.4.2	Turret and Straight Pin Terminals .....	24
4.6	Preprocessing Cleanliness Requirements .....	16	5.4.3	Bifurcated Terminals .....	25
4.7	General Part Mounting Requirements.....	16	5.4.4	Slotted Terminals .....	26
4.7.1	General Requirements.....	16	5.4.5	Hook Terminals.....	27
4.7.2	Lead Deformation Limits .....	16	5.4.6	Pierced or Perforated Terminals.....	27
4.8	Hole Obstruction.....	16	5.4.7	Cup and Hollow Cylindrical Terminals – Placement .....	27
4.9	Metal-Cased Component Isolation .....	16	5.4.8	Series Connected.....	28
4.10	Adhesive Coverage Limits .....	16	5.5	Soldering to Terminals.....	28
4.11	Mounting of Parts on Parts (Stacking of Components) .....	16	5.5.1	Bifurcated Terminals.....	28
4.12	Connectors and Contact Areas .....	16	5.5.2	Slotted Terminal.....	28
4.13	Handling of Parts.....	16	5.5.3	Cup and Hollow Cylindrical Terminals – Soldering .....	28
4.13.1	Preheating.....	17	5.6	Jumper Wires .....	29
4.13.2	Controlled Cooling .....	17	5.6.1	Insulation.....	29
4.13.3	Drying/Degassing.....	17	5.6.2	Wire Routing.....	29
4.13.4	Holding Devices and Materials.....	17	5.6.3	Wire Staking .....	29
4.14	Machine Soldering.....	17	5.6.4	Unpopulated Land or Via – Lap Soldered.....	29
4.14.1	Nonreflow Soldering .....	17	5.6.5	Supported Holes .....	29
4.14.2	Reflow Soldering .....	17	5.6.6	SMT .....	29
4.15	Solder Connection.....	17	<b>6.0</b>	<b>THROUGH-HOLE MOUNTING AND TERMINATIONS .....</b>	<b>31</b>
4.15.1	Exposed Surfaces.....	18	6.1	Through-Hole Terminations – General .....	31
4.15.2	Solder Connection Anomalies .....	18	6.1.1	Lead Forming.....	32
4.15.3	Partially Visible or Hidden Solder Connections.....	18	6.1.2	Termination Requirements.....	32
4.16	Heat Shrinkable Soldering Devices .....	18	6.1.3	Lead Trimming .....	33
4.17	Threaded Fasteners .....	19	6.1.4	Interfacial Connections .....	33
4.18	Torque .....	20	6.2	Supported Holes .....	33
<b>5.0</b>	<b>WIRES AND TERMINAL CONNECTIONS .....</b>	<b>21</b>	6.2.1	Solder Application .....	33
5.1	Wire and Cable Preparation .....	21	6.2.2	Through-Hole Component Lead Soldering.....	33
5.1.1	Insulation Damage .....	21	6.2.3	Coating Meniscus in Solder .....	34
5.1.2	Strand Damage.....	21	6.3	Unsupported Holes .....	34
5.1.3	Tinning of Stranded Wire – Forming .....	21	6.3.1	Lead Termination Requirements for Unsupported Holes .....	34
5.2	Solder Terminals .....	22	<b>7.0</b>	<b>SURFACE MOUNTING OF COMPONENTS .....</b>	<b>35</b>
5.3	Bifurcated, Turret and Slotted Terminal Installation .....	22	7.1	Surface Mount Device Lead .....	35
5.3.1	Shank Damage .....	22	7.1.1	Plastic Components.....	35
5.3.2	Flange Damage .....	22	7.1.2	Forming.....	35
5.3.3	Flared Flange Angles.....	22	7.1.3	Unintentional Bending.....	36
5.3.4	Terminal Mounting – Mechanical.....	22	7.1.4	Flat Pack Parallelism .....	36
5.3.5	Terminal Mounting – Electrical .....	22	7.1.5	Surface Mount Device Lead Bends .....	36
5.3.6	Terminal Mounting – Soldering .....	23	7.1.6	Flattened Leads .....	36
5.4	Mounting to Terminals .....	23	7.1.7	Parts Not Configured for Surface Mounting ....	36

7.2	Leaded Component Body Clearance.....	36	8.3.2	Level 2 – Minor Changes with Supporting Objective Evidence .....	64
7.2.1	Axial-Leaded Components .....	36	8.4	Foreign Object Debris (FOD) .....	64
7.3	Parts Configured for Butt/I Lead Mounting .....	36	8.5	Visible Residues.....	65
7.4	Installation of Surface Mount Components .....	36	8.6	Non-ionic Residues.....	65
7.5	Soldering Requirements.....	36	8.7	Ultrasonic Cleaning Processes .....	65
7.5.1	Misaligned Components .....	37	8.8	Guidance Documents.....	65
7.5.2	Unspecified and Special Requirements.....	37	<b>9.0</b>	<b>PRINTED BOARD REQUIREMENTS .....</b>	<b>67</b>
7.5.3	Bottom Only Chip Component Terminations... ..	38	9.1	Printed Board Damage .....	67
7.5.4	Rectangular or Square End Chip Components – 1, 2, 3 or 5 Side Termination(s).....	39	9.1.1	Blistering/Delamination .....	67
7.5.5	Cylindrical End Cap Terminations.....	41	9.1.2	Weave Exposure/Cut Fibers .....	67
7.5.6	Castellated Terminations.....	43	9.1.3	Haloing.....	67
7.5.7	Flat Gull Wing Leads .....	44	9.1.4	Edge Delamination .....	67
7.5.8	Round or Flattened (Coined) Gull Wing Leads .....	45	9.1.5	Land/Conductor Separation .....	67
7.5.9	J Lead Terminations.....	46	9.1.6	Land/Conductor Reduction in Size .....	67
7.5.10	Butt/I Terminations .....	47	9.1.7	Flexible Circuitry Delamination.....	67
7.5.11	Flat Lug Leads.....	49	9.1.8	Flexible Circuitry Damage .....	67
7.5.12	Tall Profile Components Having Bottom Only Terminations .....	50	9.1.9	Burns .....	67
7.5.13	Inward Formed L-Shaped Ribbon Leads.....	51	9.1.10	Non-Soldered Edge Contacts .....	67
7.5.14	Surface Mount Area Array Packages .....	52	9.1.11	Measles.....	67
7.5.15	Bottom Termination Components (BTC).....	55	9.1.12	Crazing .....	68
7.5.16	Components with Bottom Thermal Plane Terminations (D-Pak).....	56	9.2	Marking .....	68
7.5.17	Flattened Post Terminations .....	57	9.3	Bow and Twist (Warpage).....	68
7.5.18	P-Style Terminations.....	58	9.4	Depanelization.....	68
7.5.19	Vertical Cylindrical Cans with Outward L-Shaped Lead Terminations.....	59	<b>10.0</b>	<b>COATING, ENCAPSULATION AND STAKING (ADHESIVE).....</b>	<b>69</b>
7.5.20	Wrapped Terminals .....	61	10.1	Conformal Coating .....	69
7.5.21	Flexible and Rigid-Flex Printed Circuitry with Flat Unformed Leads .....	62	10.1.1	Materials.....	69
7.6	Specialized SMT Terminations.....	62	10.1.2	Masking.....	69
<b>8.0</b>	<b>CLEANING AND RESIDUE REQUIREMENTS .....</b>	<b>63</b>	10.1.3	Application.....	69
8.1	Qualified Manufacturing Process .....	63	10.1.4	Thickness.....	69
8.1.1	Cleaning Designator .....	63	10.1.5	Uniformity.....	69
8.2	Ionic Process Monitoring .....	63	10.1.6	Bubbles and Voids .....	69
8.2.1	Sampling Plan.....	63	10.1.7	Delamination .....	70
8.2.2	Control Limits.....	63	10.1.8	Foreign Objects Debris.....	70
8.2.3	Exceeding the Control Limits .....	64	10.1.9	Other Visual Conditions .....	70
8.3	Re-qualification Requirements .....	64	10.1.10	Inspection .....	70
8.3.1	Level 1 – Major Changes Requiring Validation .....	64	10.1.11	Rework or Touchup .....	70
			10.2	Encapsulation .....	70
			10.2.1	Application.....	70
			10.2.2	Performance Requirements.....	70

10.2.3 Rework of Encapsulant Material..... 70

10.2.4 Encapsulant Inspection ..... 70

10.3 Staking..... 70

10.3.1 Staking – Application ..... 71

10.3.2 Staking – Adhesive ..... 73

10.3.3 Staking (Inspection)..... 73

**11.0 WITNESS (TORQUE/ANTI-TAMPERING) STRIPE..... 75**

**12.0 REWORK AND REPAIR..... 77**

12.1 Rework ..... 77

12.2 Repair ..... 77

12.3 Post Rework/Repair Cleaning ..... 77

**APPENDIX A Guidelines for Soldering Tools and Equipment..... 79**

**APPENDIX B Minimum Electrical Clearance – Electrical Conductor Spacing ..... 81**

**APPENDIX C J-STD-001 Guidance on Objective Evidence of Material Compatibility .. 83**

**APPENDIX D X-Ray Guidelines ..... 87**

**Figures**

Figure 1-1 Wire Overlap..... 5

Figure 1-1 Wire Overwrap..... 5

Figure 4-1 Hole Obstruction..... 16

Figure 4-2 Acceptable Wetting Angles..... 18

Figure 4-3 Hardware Sequence and Orientation..... 19

Figure 4-4 Example of Hardware Sequence and Orientation ..... 19

Figure 5-1 Insulation Thickness ..... 21

Figure 5-2 Flange Damage ..... 22

Figure 5-3 Flared Flange Angles ..... 22

Figure 5-4 Terminal Mounting – Mechanical..... 22

Figure 5-5 Terminal Mounting – Electrical ..... 23

Figure 5-6 Insulation Clearance Measurement..... 23

Figure 5-7 Service Loop for Lead Wiring..... 23

Figure 5-8 Stress Relief Examples ..... 24

Figure 5-9 Insulation Sleeving ..... 24

Figure 5-10 Wire and Lead Placement..... 24

Figure 5-11 Bifurcated Terminal Side Route Placement with Wrap ..... 25

Figure 5-12 Bifurcated Terminal Side Route Placement – Straight Though and Staked ..... 25

Figure 5-13 Bifurcated Terminal Top and Bottom Route Connection..... 26

Figure 5-14 Slotted Terminal..... 26

Figure 5-15 Hook Terminal Wire Placement..... 27

Figure 5-16 Acceptable Pierced or Perforated Terminal Wire Placement ..... 27

Figure 5-17 Wires on Intermediate Turret, Bifurcated, and Pierced Terminals..... 28

Figure 5-18 Solder Depression ..... 28

Figure 5-19 Cup and Hollow Cylindrical Terminals – Vertical Fill of Solder ..... 29

Figure 6-1 Component Lead Stress Relief Examples ..... 31

Figure 6-2 Lead Bends ..... 32

Figure 6-3 Lead Trimming..... 33

Figure 6-4 Vertical Fill Example ..... 34

Figure 7-1 Surface Mount Device Lead Forming ..... 35

Figure 7-2 Surface Mount Device Lead Forming ..... 35

Figure 7-3 Bottom Only Terminations ..... 38

Figure 7-4 Rectangular or Square End Chip Components ..... 39

Figure 7-4A Rectangular or Square End Chip Components – 1, 2, 3 or 5 Side Termination(s) Center Termination (When Present) ..... 40

Figure 7-5 Cylindrical End Cap Terminations ..... 41

Figure 7-5A Cylindrical End Cap Terminations Center Termination (When Present)..... 42

Figure 7-6 Castellated Terminations ..... 43

Figure 7-7 Flat Gull Wing Leads..... 44

Figure 7-8 Round or Flattened (Coined) Gull Wing Leads..... 45

Figure 7-9 J Leads..... 46

Figure 7-10 Butt/I Terminations for Modified Through-Hole Leads..... 47

Figure 7-11 Butt/I Terminations for Solder Charged Leads..... 48

Figure 7-12 Flat Lug Leads..... 49

Figure 7-12A SMD-4 LED ..... 49

Figure 7-13 Tall Profile Components Having Bottom Only Terminations..... 50

Figure 7-14 Inward Formed L-Shaped Ribbon Lead..... 51

Figure 7-15 BGA Solder Ball Clearance ..... 53

Figure 7-16 Bottom Termination Component..... 55

Figure 7-17 Bottom Thermal Plane Termination ..... 56

Figure 7-18 Flattened Post Termination..... 57

Figure 7-19 P-Style Termination ..... 58

Figure 7-20 Examples of Vertical Cylindrical Cans with Outward L-Shaped Lead Terminations..... 60

Figure 7-21 Vertical Cylindrical Cans with Outward L-Shaped Lead Terminations ..... 60

Figure 7-22 Wrapped Terminal – SMT Inductor – Bottom View ..... 61

Figure 7-23	Wrapped Terminal – SMT Inductor – Top View .....	61	Table 6-2	Components with Spacers .....	31
Figure 7-24	Wrapped Terminal – SMT Component.....	61	Table 6-3	Lead Bend Radius.....	32
Figure 7-25	Wrapped Terminals.....	61	Table 6-4	Protrusion of Leads in Supported Holes .....	33
Figure 7-26	Flexible and Rigid-Flex Circuitry with Flat Unformed Leads.....	62	Table 6-5	Protrusion of Leads in Unsupported Holes ....	33
Figure 10-1	Radial Leded Components Whose Height Is Greater Than or Equal to Their Length or Diameter – Individual Rectangular Shaped Component .....	71	Table 6-6	Supported Holes with Component Leads, Minimum Acceptable Conditions, Note 1 .....	34
Figure 10-2	Radial Leded Components Whose Height Is Greater Than or Equal to Their Length or Diameter – Individual Cylindrically Shaped Component .....	72	Table 6-7	Unsupported Holes with Component Leads, Minimum Acceptable Conditions, Notes 1, 4.....	34
Figure 10-3	Radial Leded Components Whose Longest Dimension Is Their Diameter or Length, e.g., TO5 Semiconductors.....	72	Table 7-1	SMT Lead Forming Minimum Lead Length (L) .....	35
Figure 10-4	Radial Leded Components Whose Height Is Greater Than or Equal to Their Length or Diameter – Closely Spaced Arrays .....	72	Table 7-2	Surface Mount Components Soldering Requirements .....	37
Figure 11-1	Torque Stripe on Fastener – Acceptable.....	75	Table 7-3	Dimensional Criteria – Bottom Only Chip Component Terminations.....	38
Figure 11-2	Torque Stripe on Fastener – Defect.....	75	Table 7-4	Dimensional Criteria – Rectangular or Square End Chip Components – 1, 2, 3 or 5 Side Termination(s) .....	39
Figure D-1	Circumferential Solder Separation .....	87	Table 7-4A	Dimensional Criteria – Center Termination (When Present) – Rectangular or Square End Chip Components – 1, 2, 3 or 5 Side Termination(s).....	40
Figure D-2	Solder Voids .....	87	Table 7-5	Dimensional Criteria – Cylindrical End Cap Terminations .....	41
<b>Tables</b>			Table 7-5A	Dimensional Criteria – Center Termination (When Present) – Cylindrical End Cap Terminations .....	42
Table 1-1	Design, Fabrication and Acceptability Specifications.....	1	Table 7-6	Dimensional Criteria – Castellated Terminations .....	43
Table 1-2	Magnification Aid Applications for Solder Connections.....	7	Table 7-7	Dimensional Criteria – Flat Gull Wing Leads .....	44
Table 1-3	Magnification Aid Applications for Wires and Wire Connections, Note 1 .....	7	Table 7-8	Dimensional Criteria – Round or Flattened (Coined) Gull Wing Leads .....	45
Table 1-4	Magnification Aid Applications – Other.....	7	Table 7-9	Dimensional Criteria – J Leads .....	46
Table 3-1	Maximum Limits of Solder Bath Contaminant .....	12	Table 7-10	Dimensional Criteria – Butt/I Connections .....	47
Table 4-1	Solder Connection Anomalies .....	18	Table 7-11	Dimensional Criteria – Butt/I Terminations – Solder Charged Terminations.....	48
Table 5-1	Allowable Strand Damage, Notes 1, 2, 3.....	21	Table 7-12	Dimensional Criteria – Flat Lug Leads, Note 5.....	49
Table 5-2	Terminal Mounting Minimum Soldering Requirements .....	23	Table 7-13	Dimensional Criteria – Tall Profile Components Having Bottom Only Terminations .....	50
Table 5-3	Turret and Straight Pin Wire Wrap.....	24	Table 7-14	Dimensional Criteria – Inward Formed L-Shaped Ribbon Leads, Note 5.....	51
Table 5-4	AWG 30 and Smaller Wire Wrap .....	25	Table 7-15	Dimensional Criteria – Ball Grid Array Components with Collapsing Balls.....	53
Table 5-5	Bifurcated Terminal Wire Placement – Side Route with Wrap .....	25	Table 7-16	Ball Grid Array Components with Noncollapsing Balls .....	54
Table 5-6	Bifurcated Terminal Side Route Straight-Through Staking.....	25	Table 7-17	Column Grid Array .....	54
Table 5-7	Bifurcated Terminal Wire Placement – Bottom Route.....	26	Table 7-18	Dimensional Criteria – BTC.....	55
Table 5-8	Hook Terminal Wire Placement.....	27	Table 7-19	Dimensional Criteria – Bottom Thermal Plane Terminations.....	56
Table 5-9	Pierced or Perforated Terminal Wire Placement.....	27			
Table 5-10	Solder Requirements Lead/Wire to Post.....	28			
Table 6-1	Component to Land Clearance .....	31			

Table 7-20	Dimensional Criteria – Flattened Post Terminations .....	57
Table 7-21	Dimensional Criteria – P-Style Terminations .....	58
Table 7-22	Dimensional Criteria – Vertical Cylindrical Cans with Outward L-Shaped Lead Terminations .....	59
Table 7-23	Dimensional Criteria – Wrapped Terminals....	61
Table 7-24	Dimensional Criteria – Flexible and Rigid-Flex Circuitry with Flat Unformed Leads .....	62
Table 8-1	Designation of Surfaces to be Cleaned .....	63
Table 8-2	Residue Testing For Process Control .....	63
Table 8-3	Maximum Acceptable Rosin, Note 1 .....	65
Table 10-1	Coating Thickness .....	69



# Requirements for Soldered Electrical and Electronic Assemblies

## 1.0 GENERAL

**1.1 Scope** This standard describes materials, methods and acceptance criteria for producing soldered electrical and electronic assemblies. The intent of this document is to rely on process control methodology to ensure consistent quality levels during the manufacture of products. It is not the intent of this standard to exclude any procedure, such as for component placement or for applying flux and solder used to make the electrical connection.

The soldering operations, equipment, and conditions described in this document are based on electrical/electronic circuits designed and fabricated in accordance with the specifications listed in Table 1-1.

**Table 1-1 Design, Fabrication and Acceptability Specifications**

Board Type	Design	Fabrication/Acceptability Specification
Generic Requirements	IPC-2221	IPC-6011
Rigid Printed Boards	IPC-2222	IPC-6012 IPC-A-600
Flexible Circuits	IPC-2223	IPC-6013
Rigid Flex Board	IPC-2222 IPC-2223	IPC-6013

**1.2 Purpose** This standard prescribes material requirements, process requirements, and acceptability requirements for the manufacture of soldered electrical and electronic assemblies. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001, IPC-AJ-820 and IPC-A-610. Standards may be updated at any time, including with the addition of amendments. The use of an amendment or a newer revision is not automatically required.

**1.3 Classification** This standard recognizes that electrical and electronic assemblies are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in manufacturability, complexity, functional performance requirements, and verification (inspection/test) frequency.

Use of this standard requires agreement on the class to which the product belongs. The User has the responsibility for identifying the class to which the assembly is produced. The product class should be stated in the procurement documentation package. If the User does not establish and document the acceptance class, the Manufacturer may do so.

### CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

### CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically the end-use environment would not cause failures.

### CLASS 3 High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

**1.4 Measurement Units and Applications** This standard uses International System of Units (SI) units per ASTM SI10, IEEE/ASTM SI 10, Section 3 [Imperial English equivalent units are in brackets for convenience]. The SI units used in this standard are millimeters (mm) [in] for dimensions and dimensional tolerances, Celsius (°C) [°F] for temperature and temperature tolerances, grams (g) [oz] for weight, and lux for illuminance.

**Note:** This standard uses other SI prefixes (ASTM SI10, Section 3.2) to eliminate leading zeroes (for example, 0.0012 mm becomes 1.2 μm) or as alternative to powers-of-ten (3.6 x 10<sup>3</sup> mm becomes 3.6 m).